



Discription

The HESDBM3V3A1 protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD. It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.



DFN1006-2L
(SOD-882)

Features

- ★ Small Body Outline Dimensions
- ★ Low Body Height
- ★ Peak Power up to 105 Watts @ 8 x 20 μ s Pulse
- ★ Low Leakage current
- ★ Response Time is Typically < 1 ns
- ★ ESD Rating of Class 3 per Human Body Model



Circuit Diagram

Ordering information

Product ID	Pack	Qty(PCS)
HESDBM3V3A1	DFN1006-2L(SOD-882)	10000

Absolute Ratings ($T_{amb}=25^{\circ}\text{C}$)

Symbol	Parameter	Value	Units
P _{PP}	Peak Pulse Power (t _p = 8/20μ s)	100	W
T _L	Maximum lead temperature for soldering during 10s	260	°C
T _{stg}	Storage Temperature Range	-55 to +150	°C
T _{op}	Operating Temperature Range	-55 to +150	°C
T _j	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD)		



Electrical Characteristics

Device	V_{RWM} (V)	I_R (μ A) @ V_{RWM}	V_{BR} (V) @ I_T (Note 1)		I_T	V_C (V) @ $I_{PP} = 1$ A (Note 2)	V_C (V) @ MAX I_{PP} (Note 2)	I_{PP} (A) (Note 2)	P_{PK} (W) (Note 2)	C (pF)	$R_{DYN}(\Omega)$ @ $t_p=100$ ns(TLP)
	Max	Max	Min	Max	mA	Max	Max	Max	Max	Typ.	Typ.
HESDBM3V3A1	3.3	0.05	5	6.5	1.0	7	11	9	100	15	0.2

- V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C.
- Surge current waveform per Figure 1.

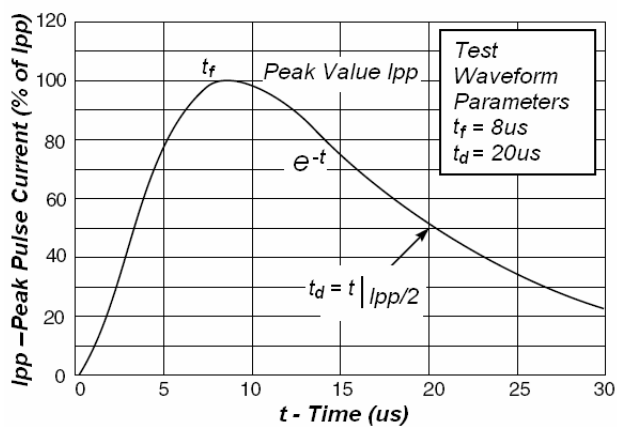


Fig1. Pulse Waveform

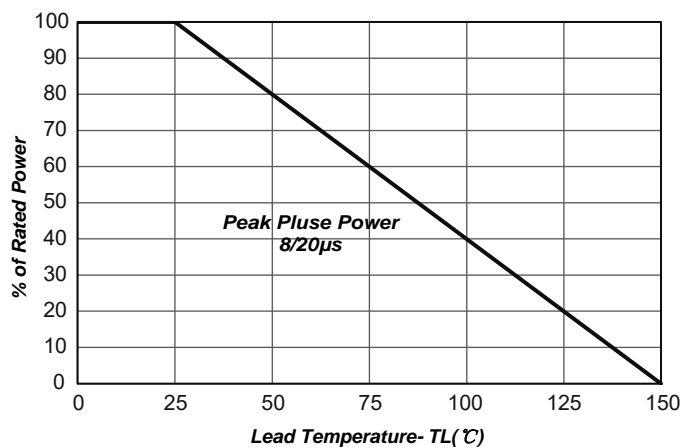


Fig2. Power Derating Curve

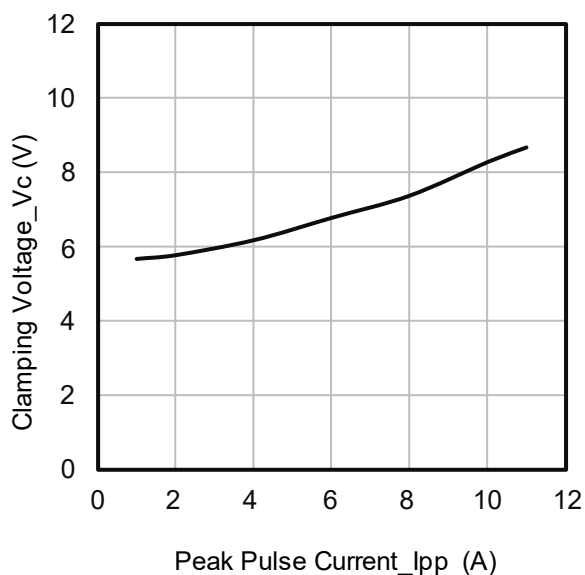


Fig3. Clamping Voltage vs. Peak Pulse Current

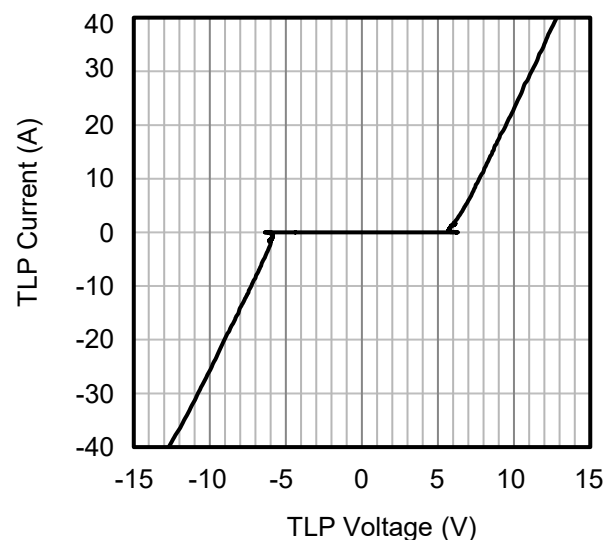
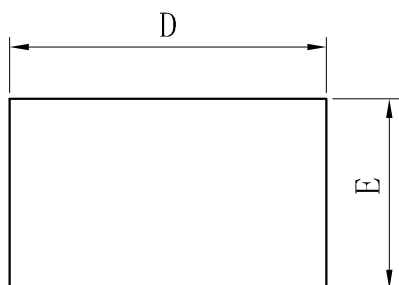


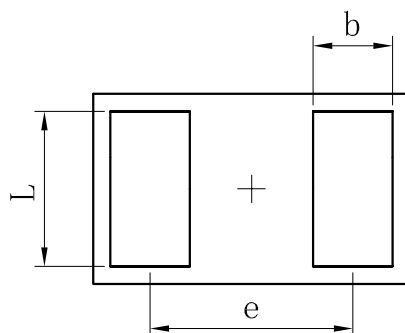
Fig4. TLP Measurement



OUTLINE AND DIMENSIONS

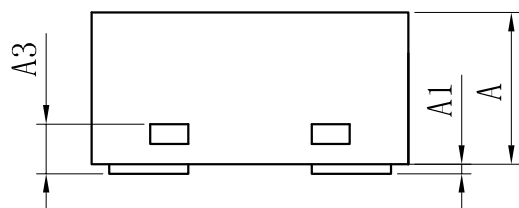


TOP VIEW



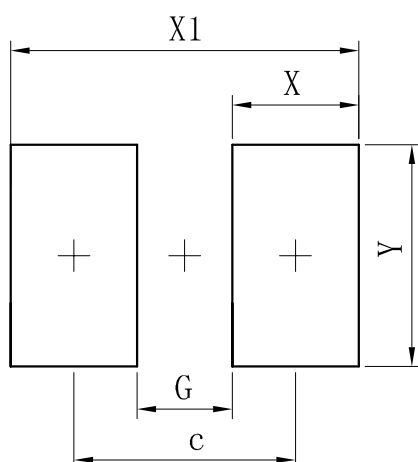
BOTTOM VIEW

DFN1006-2L(SOD-882)			
Dim	Min	Typ	Max
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e	—	0.64	—
L	0.44	0.49	0.54
b	0.20	0.25	0.30
A	0.43	0.48	0.53
A1	0	—	0.05
A3	0.127REF.		
All Dimensions in mm			



SIDE VIEW

SOLDERING FOOTPRINT



Dimensions	(mm)
c	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70



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